

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.10233	100.0	1.701
Subtotal				0.10233	100	1.701
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.02226	100.0	0.37
Subtotal				0.02226	100	0.37
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00987	2.0	0.164
	Lead alloy	Silver (Ag)	7440-22-4	0.01233	2.5	0.205
	Lead alloy	Lead (Pb)	7439-92-1	0.4711	95.5	7.831
	Subtotal			0.4933	100	8.2
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01294	0.03	0.2151
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01294	0.03	0.2151
	Copper alloy	Iron (Fe)	7439-89-6	0.04313	0.1	0.717
	Copper alloy	Copper (Cu)	7440-50-8	43.06475	99.84	715.8528
Subtotal				43.13376	100	717
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	2.18978	4.0	36.4
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	8.21166	15.0	136.5
	Filler	Silica fused	60676-86-0	40.51084	74.0	673.4
	Flame retardant	Metal hydroxide		3.83211	7.0	63.7
Subtotal				54.74439	100	910
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.50397	100.0	25
Subtotal				1.50397	100	25
Total				100.00001	100	1662.271

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